TOSHIBA Field-Effect Transistor Silicon P-Channel MOS Type

# SSM3J304T

- O Power Management Switch Applications
- High-Speed Switching Applications

1.8 V drive

• Low ON-resistance:  $R_{on} = 297 \text{ m}\Omega \text{ (max) } (@V_{GS} = -1.8 \text{ V})$ 

 $R_{on}$  = 168 m $\Omega$  (max) (@V<sub>GS</sub> = -2.5 V)

 $R_{on} = 127 \text{ m}\Omega \text{ (max) } (@V_{GS} = -4.0 \text{ V})$ 

# **Absolute Maximum Ratings (Ta = 25°C)**

Characteristic	Symbol	Rating	Unit		
Drain-source voltage	$V_{DS}$	-20	V		
Gate-source voltage	$V_{GSS}$	± 8	V		
Drain current	DC	ΙD	-2.3	Α	
	Pulse	I <sub>DP</sub>	-4.6		
Drain power dissipation		P <sub>D</sub> (Note 1)	700	mW	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature	T <sub>stg</sub>	-55~150	°C		

Note:

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on an FR4 board

 $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 1.6 \text{ t}, \text{ Cu Pad: } 645 \text{ mm}^2)$ 

# 1. GATE 2. SOURCE 3. DRAIN TSM JEDEC JEITA TOSHIBA 2.8 ± 0.2 3 1.6 ± 0.2 1 1.0 4 + 0.0 1.0 4 + 0.0 1.0 4 + 0.0 1.0 50 0 +

Weight: 10 mg (typ.)

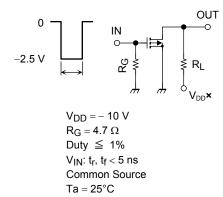
## **Electrical Characteristics (Ta = 25°C)**

Charac	teristic	Symbol	Test Condition		Min	Тур.	Max	Unit	
Drain-source breakdown voltage		V (BR) DSS	$I_D = -1 \text{ mA}, V_{GS} = 0$		-20	_	_	V	
		V (BR) DSX	$I_D = -1 \text{ mA}, V_{GS} = +8 \text{ V}$		-12	_	_		
Drain cutoff current		I <sub>DSS</sub>	V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0		_	_	-10	μА	
Gate leakage curre	nt	I <sub>GSS</sub>	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0$		_	_	±1	μΑ	
Gate threshold volta	age	V <sub>th</sub>	$V_{DS} = -3 \text{ V}, I_{D} = -1 \text{ mA}$		-0.3	_	-1.0	V	
Forward transfer ac	Imittance	Y <sub>fs</sub>	$V_{DS} = -3 \text{ V}, I_{D} = -1 \text{ A}$ (Not	te 2)	2.4	4	_	S	
Drain-source ON-resistance		R <sub>DS</sub> (ON)	$I_D = -1.0 \text{ A}, V_{GS} = -4 \text{ V}$ (Not	te 2)	_	88	127	mΩ	
			$I_D = -0.5 \text{ A}, V_{GS} = -2.5 \text{ V}$ (Not	te 2)	_	120	168		
			$I_D = -0.2 \text{ A}, V_{GS} = -1.8 \text{ V}$ (Not	te 2)	_	172	297		
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0, f = 1 MHz		_	335		pF	
Output capacitance		Coss			_	70			
Reverse transfer capacitance C <sub>rss</sub>				_	56				
Switching time	Turn-on time	t <sub>on</sub>	$V_{DD} = -10 \text{ V}, I_D = -1\text{A},$ $V_{GS} = 0 \sim -2.5 \text{ V}, R_G = 4.7 \Omega$		_	20		ns	
	Turn-off time	t <sub>off</sub>			_	20	_		
Drain-source forward voltage		V <sub>DSF</sub>	$I_D = 2.3 \text{ A}, V_{GS} = 0$ (Note 2)		_	0.85	1.2	V	

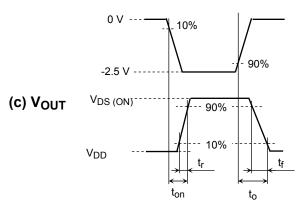
Note 2: Pulse test

# **Switching Time Test Circuit**

### (a) Test circuit

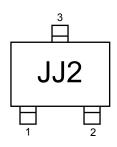


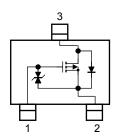
### (b) V<sub>IN</sub>



# Marking

# **Equivalent Circuit (top view)**





# **Notice on Usage**

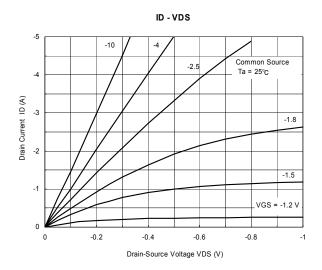
 $V_{th}$  can be expressed as the voltage between gate and source when the low operating current value is  $I_D$  = -1 mA for this product. For normal switching operation,  $V_{GS}$  (on) requires a higher voltage than  $V_{th}$  and  $V_{GS}$  (off) requires a lower voltage than  $V_{th}$ .

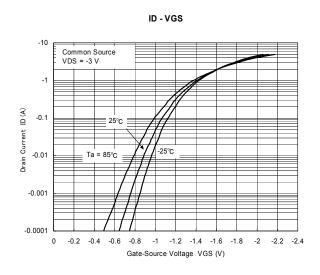
(The relationship can be established as follows:  $V_{GS\ (off)}$  <  $V_{th}$  <  $V_{GS\ (on)}$ .)

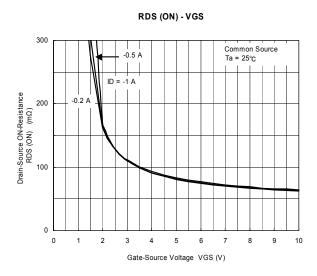
Take this into consideration when using the device. )

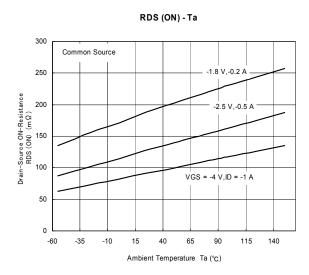
### **Handling Precaution**

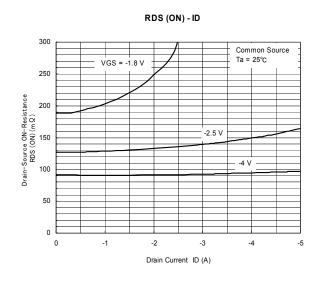
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

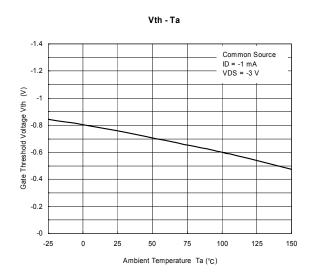


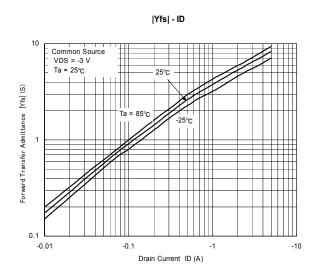


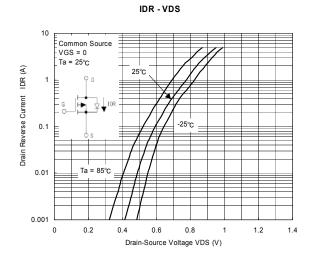


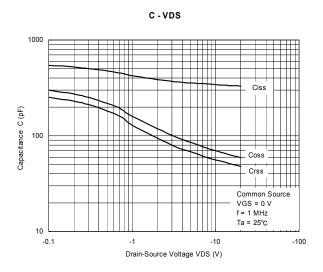


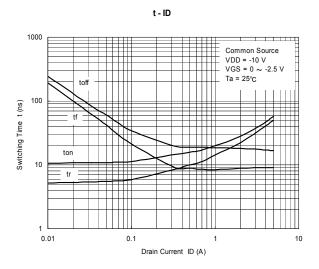


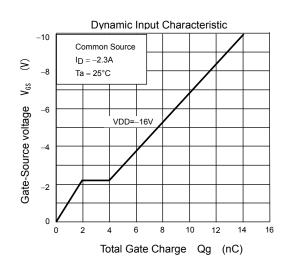


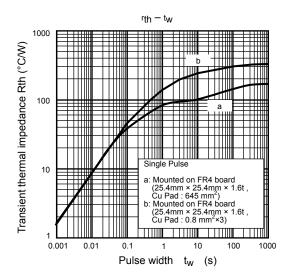


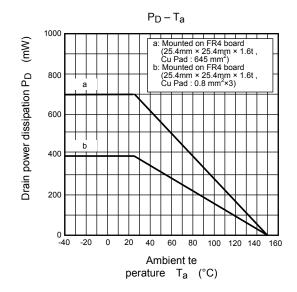












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20070701-EN GENERAL

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